DESCRIPTION

The SS22A_SS220A are available in SMA package.

FEATURE

- Metal Silicon Junction, Majority Carrier Conduction
- For Surface Mounted Applications
- Low Power Loss, High Efficiency
- High Forward Surge Current Capability
- For use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.07g / 0.002oz

ORDERING INFORMATION

Package Type	Part Number
SMA	SS22A
	SS24A
	SS26A
	SS28A
	SS210A
	SS212A
	SS215A
	SS220A
Note	SPQ: 5,000pcs/Reel
AiT provides all RoHS Compliant Products	

PIN DESCRIPTION

SMA

PIN#	DESCRIPTION
1	CATHODE
2	ANODE

ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase, half wave ,60Hz, resistive or inductive load, for capacitive load, derate by 20 %.

Parameter		Symbol	SS22A	SS24A	SS26A	SS28A	SS210A	SS212A	SS215A	SS220A	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage		V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage		V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current		$I_{F(AV)}$	2								A
Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)		I_{FSM}	50								A
Maximum Instantaneous Forward Voltage at 2A		V_F	0.55	0.55	0.70	0.70	0.85	0.85	0.90	0.90	V
Maximum Instantaneous Reverse Current at Rated DC Reverse Voltage	T_A=25℃	I_R	0.50	0.50	0.50	0.30	0.30	0.30	0.30	0.30	mA
	T_A=100℃		5	5	5	3	3	3	3	3	
Typical Junction Capacitance (1)		C_J	220	220	80	80	80	80	80	80	pF
Typical Thermal Resistance (2)		$R_{\theta JA}$	80								℃/W
Operating Junction Temperature Range		T_J	-55 ~ + 150								℃
Storage Temperature Range		T_{STG}	-55 ~ + 150								℃

TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Forward Current Derating Curve

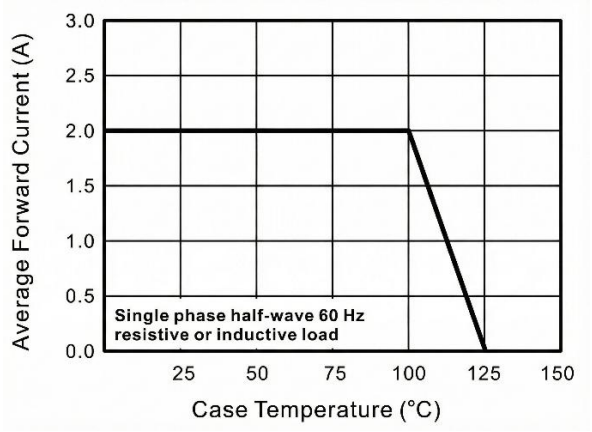


Fig 2. Typical Reverse Characteristics

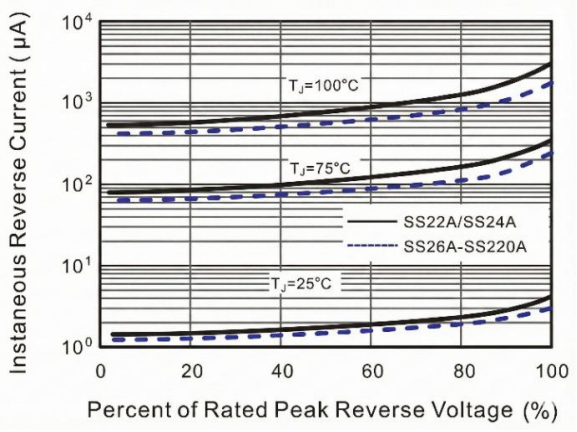


Fig 3. Typical Forward Characteristics

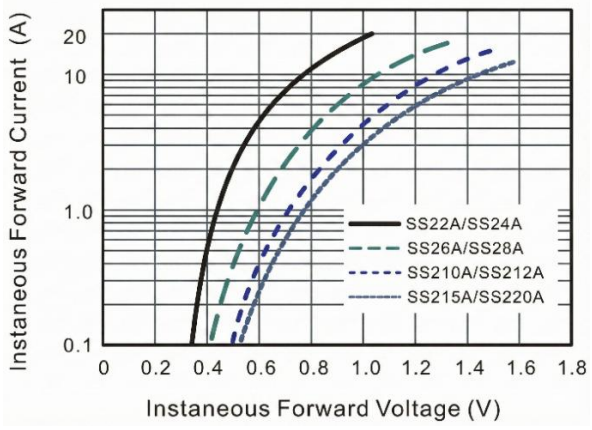


Fig 4. Typical Junction Capacitance

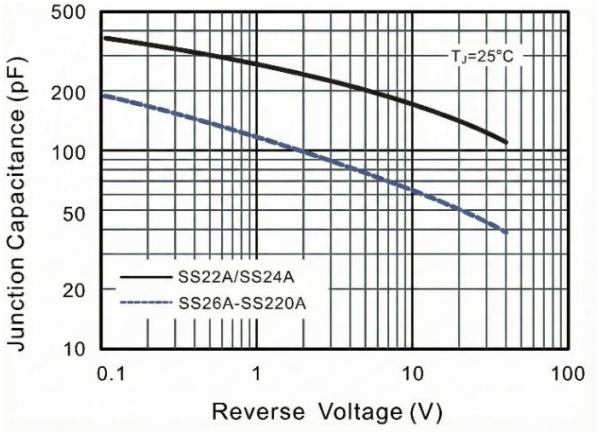


Fig 5. Maximum Non-Repetitive Peak Forward Surge Current

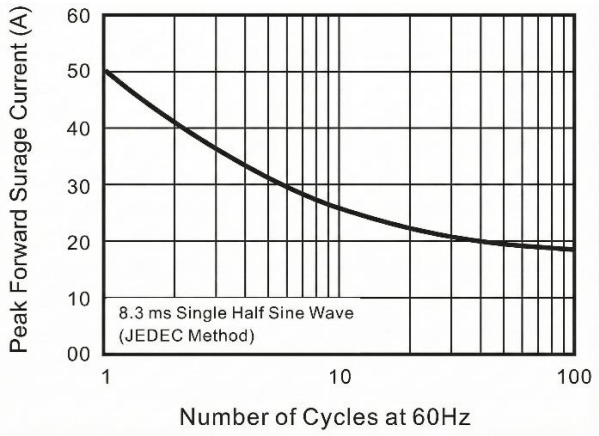
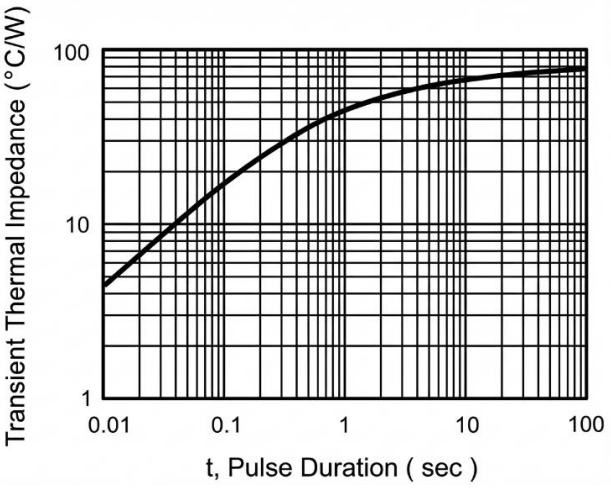
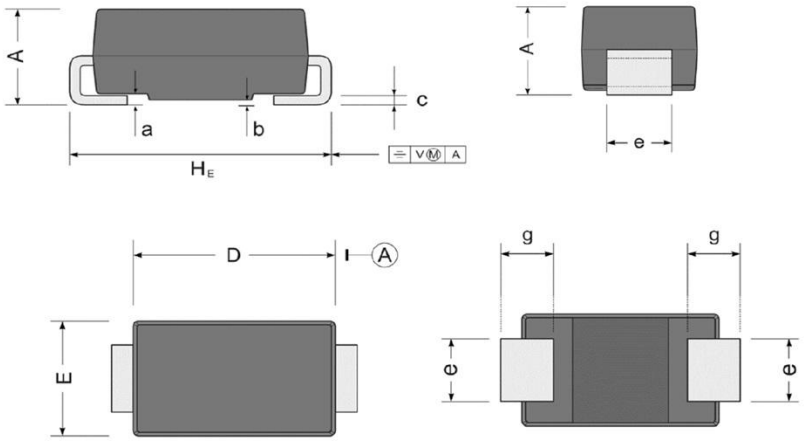


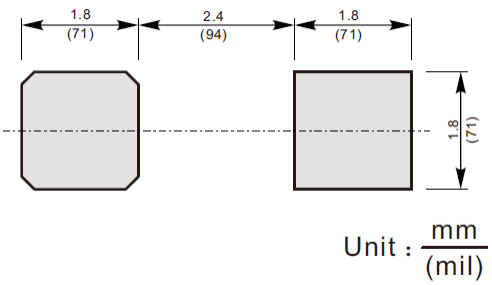
Fig 6. Typical Transient Thermal Impedance



PACKAGE INFORMATION

Dimension in SMA Package





The Recommended Mounting Pad Size

DIM	MILLIMETERS	
	MIN	MAX
A	1.900	2.450
a	0.300	
b	0.050	0.200
c	0.150	0.310
D	4.000	4.500
E	2.500	2.800
e	1.300	1.800
g	0.900	1.500
H_E	4.700	5.200

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